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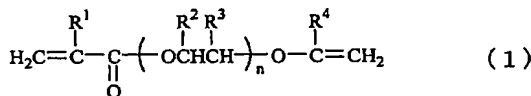


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- (71) Applicants (for all designated States except US): **DSM IP ASSESTS B.V.** [NL/NL]; Het Overloon 1, NL-6411 TE Heerlen (NL). **JSR CORPORATION** [JP/JP]; 5-6-10, Tsukiji Chuo-ku, Tokyo 104-8410 (JP).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): **TAKAHASHI, Atsuya** [JP/JP]; 2-13-28-504, Kawaguchi, Tsuchiura-Shi 300-0033 (JP). **SHIGEMOTO, Takeo** [JP/JP]; 4-1-603 Izumi, Abiko, Chiba 270-1142 (JP). **KOMIYA, Zen** [JP/JP]; 2-18-33 M1-3, Umezono, Tsukuba 305-0045 (JP). **OHARA, Hiroki**; 3-17-1-404, Namiki, Tsukuba 305-0044 (JP).
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- (74) Agent: **VERWEIJ, P., D.**; DSM Intellectual Property, P.O. Box 9, NL-6160 MA Geleen (NL).
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(57) Abstract: The invention relates to a radiation -curable liquid resin composition comprising: (A) 20-90 wt% of a urethane (meth)acrylate oligomer, and (B) 1-35 wt% of - a monomer shown by the following formula (1), wherein R¹ represents a hydrogen atom or a methyl group, R² and R³ individually represent a hydrogen atom or an alkyl group having 1-4 carbon atoms, R⁴ represents a hydrogen atom or a methyl group, and n represents an integer of 1-6, or - a monomer including a hydroxyl group.